Title: Apparatus and process for precise encapsulation of flip chip interconnects
Inventor: Pendse
Appln. No. 10/081,425

1/1

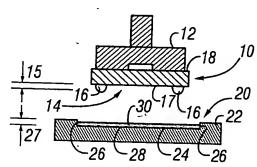


FIG. 1

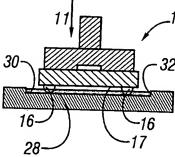


FIG. 2

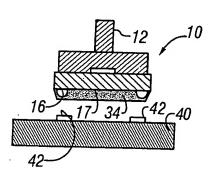


FIG. 3

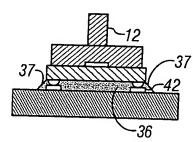


FIG. 4

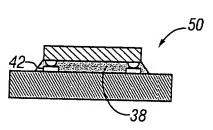


FIG. 5